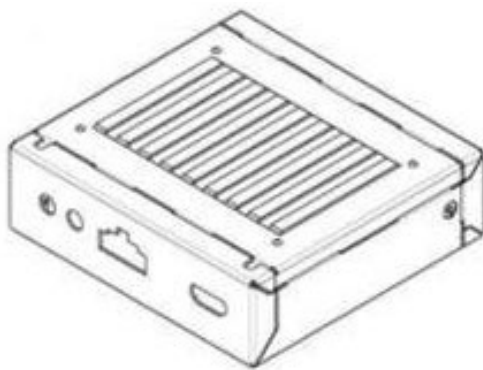


INDUSTRY 4.0 APPLICATION



REQUIREMENT

Based on Interscale C for e-NUC. Customer requirement: Housing for a PCB based on the embedded NUC form factor conform to SDT.03 specification.



CHALLENGE

Cool the processor of the e-NUC board efficiently. Add an opportunity to assemble the box on a Din-Rail.



SOLUTION

Cooling fins 1 mm and heat block work together. Heat dissipation >8W. Reduction of assembly.

Project Details

Location	Germany
Type of system	Embedded NUC form factor based IOT / Industry 4.0 solution
Technology	E-NUC Board based on SDt.03 specification
Product scope	Series
Date/Time frame	11 / 2015
Contract scope	> 500 boxes per year